



(12) **United States Design Patent**
Vincent et al.

(10) **Patent No.:** **US D684,130 S**
(45) **Date of Patent:** **** Jun. 11, 2013**

(54) **ELECTRONICS ENCLOSURE**

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(**) Term: **14 Years**

(21) Appl. No.: **29/422,058**

(22) Filed: **May 16, 2012**

(51) **LOC (9) Cl.** **13-03**

(52) **U.S. Cl.**
USPC **D13/184**

(58) **Field of Classification Search**
USPC D14/300, 301, 308, 314, 348, 349-356, D14/358; D13/162, 184, 199; 312/223.1-223.2; 360/99.01-99.12; 369/34.01, 36.01; 361/679.01, 679.6, 679.22; 345/173
See application file for complete search history.

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Primary Examiner — Freda S Nunn

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(57) **CLAIM**

The ornamental design for an electronics enclosure, as shown and described.

DESCRIPTION

FIG. 1 is a perspective view of our design; FIG. 2 is a top plan view of the embodiment of FIG. 1; FIG. 3 is a side elevational view of the embodiment of FIG. 1, the opposite side being a mirror image thereof; FIG. 4 is a front elevational view of the embodiment of FIG. 1; FIG. 5 is a back view of the embodiment of FIG. 1; FIG. 6 is a perspective view of a second embodiment of our design; FIG. 7 is a top plan view of the embodiment of FIG. 6; FIG. 8 is a side elevational view of the embodiment of FIG. 6, the opposite side being a mirror image thereof; FIG. 9 is a front view of the embodiment of FIG. 6; FIG. 10 is a back view of the embodiment of FIG. 6; FIG. 11 is a perspective view of a third embodiment of our design; FIG. 12 is a top plan view of the embodiment of FIG. 11; FIG. 13 is a side elevational view of the embodiment of FIG. 11, the opposite side being a mirror image thereof; FIG. 14 is a front view of the embodiment of FIG. 11; and, FIG. 15 is a back view of the embodiment of FIG. 11. Broken lines shown in the drawings illustrate portions of the electronics enclosure, and form no part of the claimed design.

1 Claim, 9 Drawing Sheets

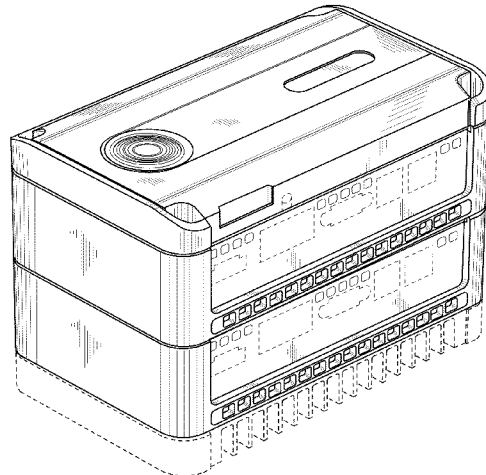
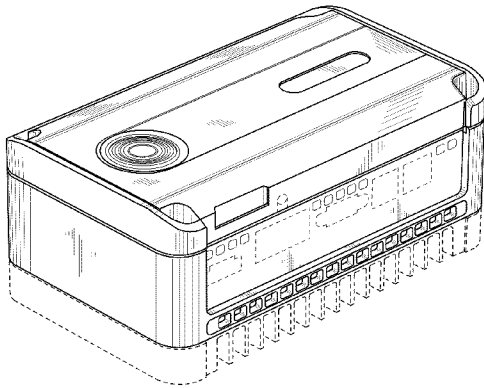


Figure 1

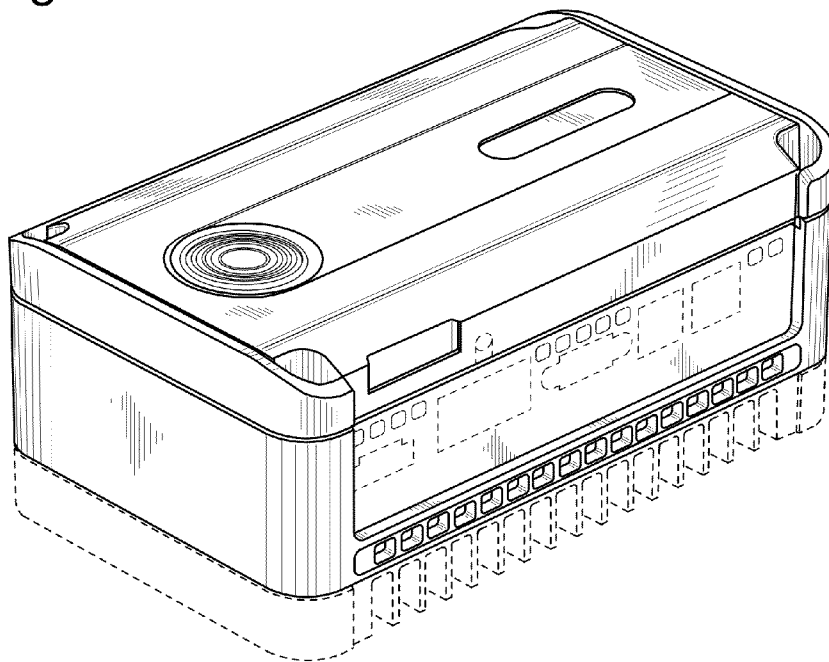


Figure 2

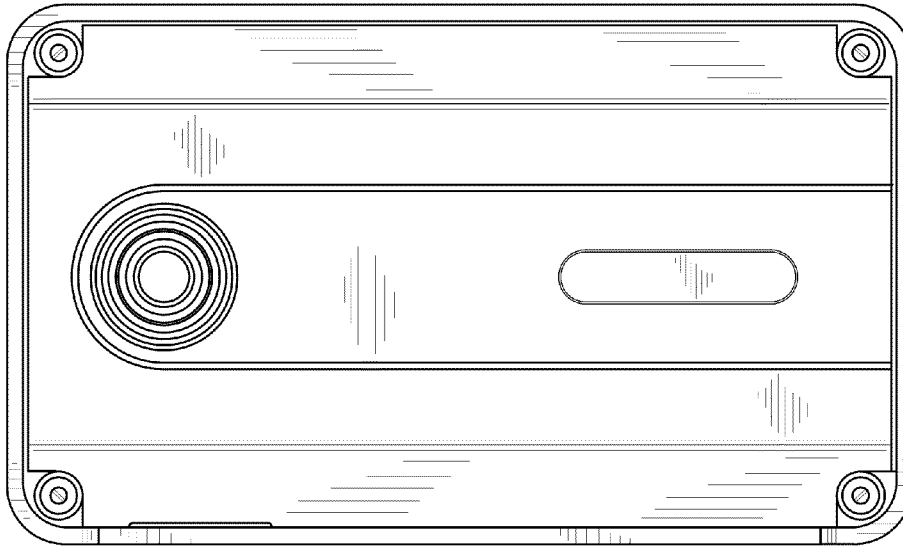


Figure 3

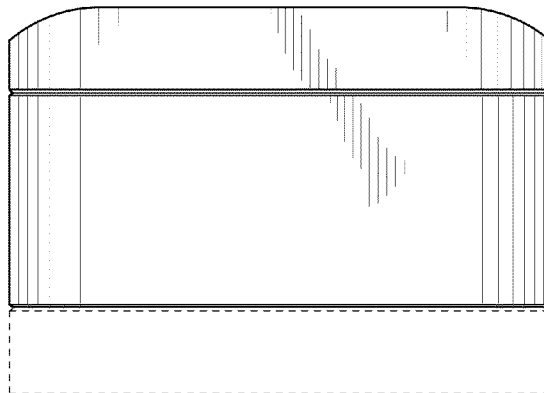


Figure 4

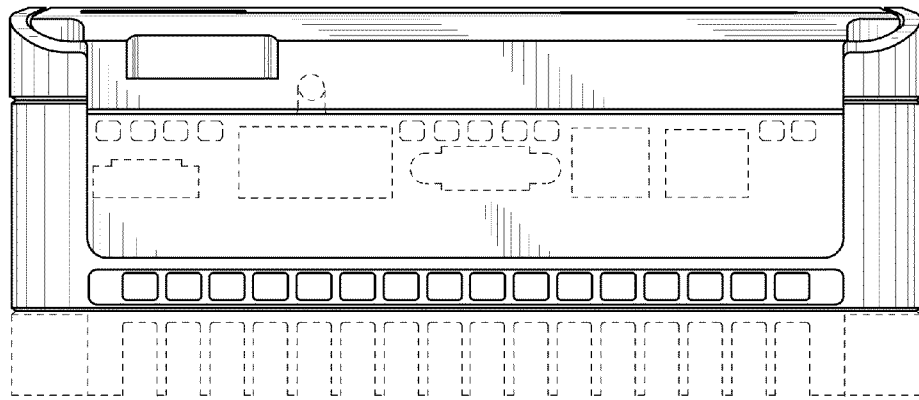


Figure 5

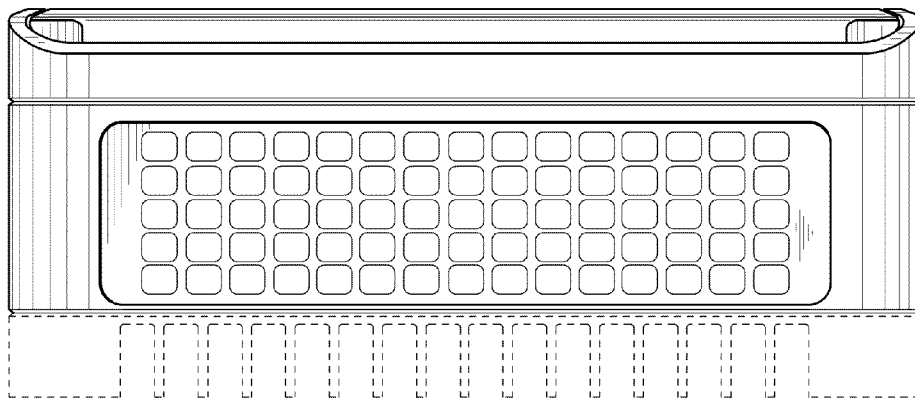


Figure 6

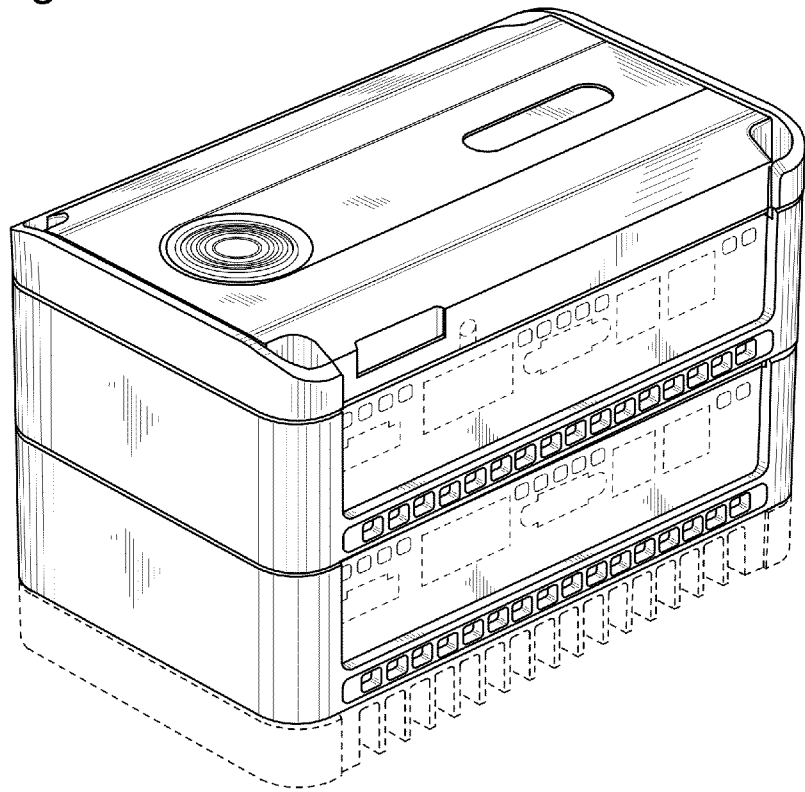


Figure 7

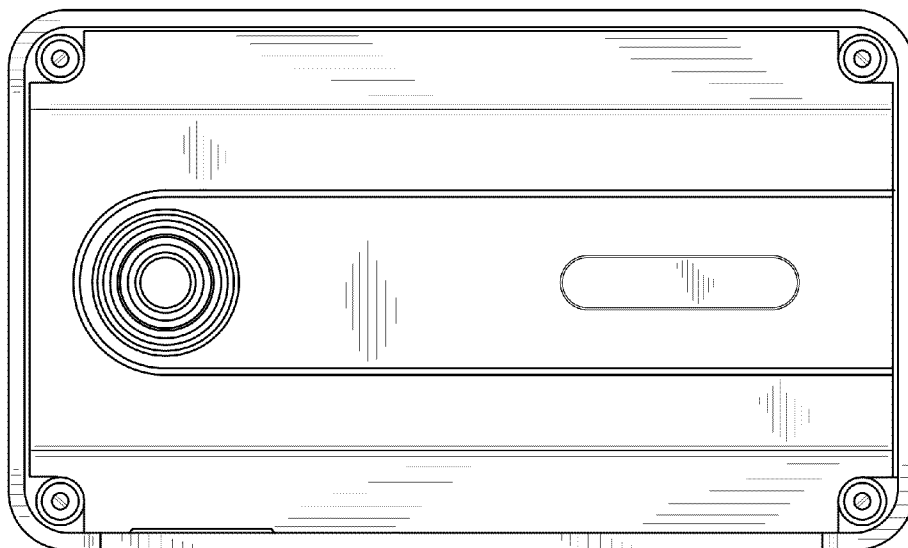


Figure 8

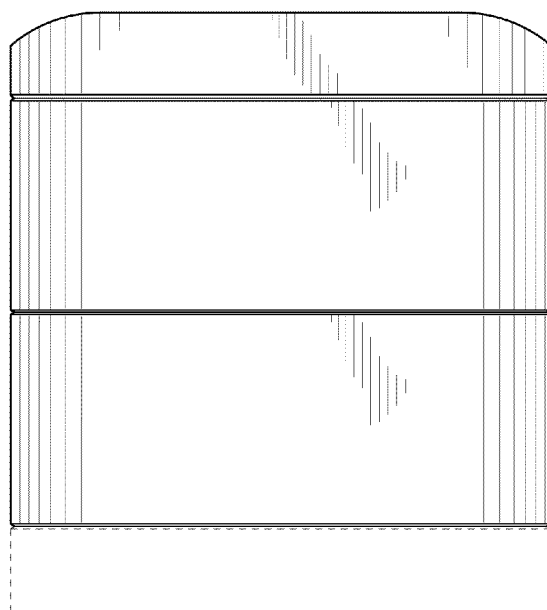


Figure 9

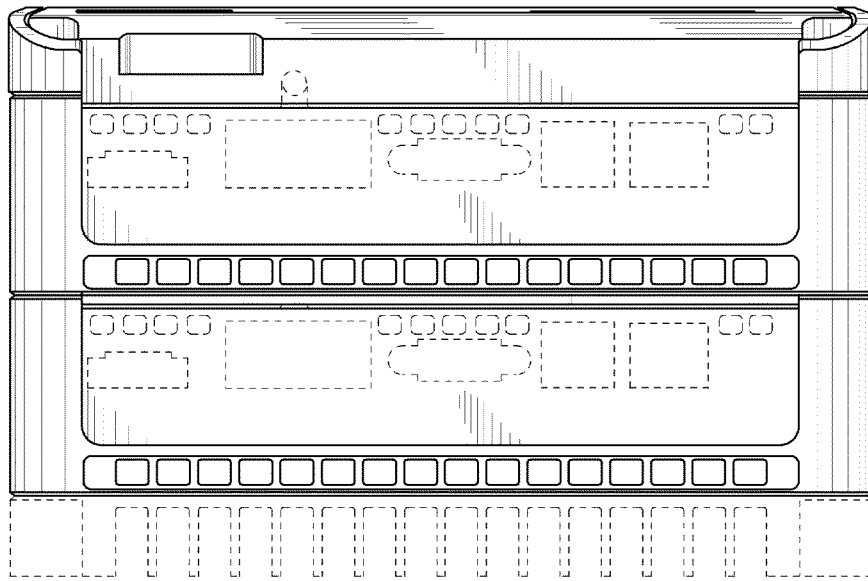


Figure 10

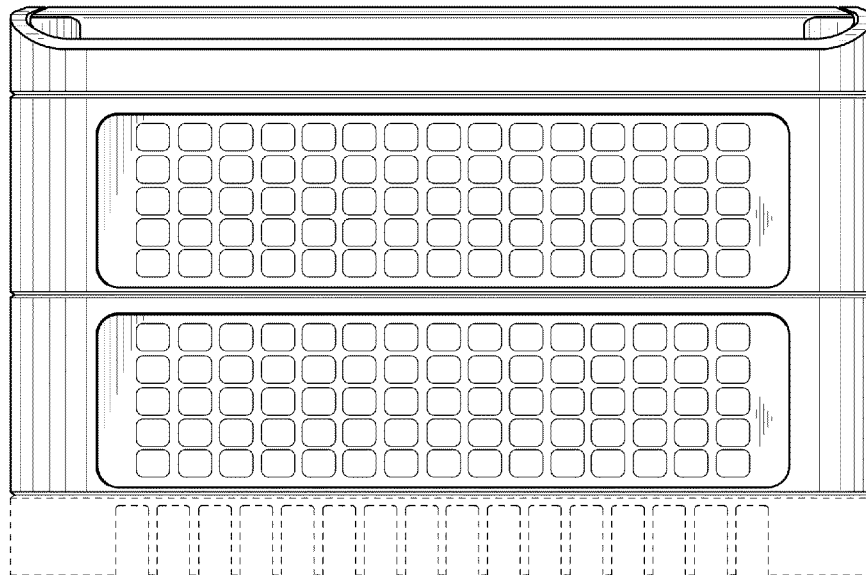


Figure 11

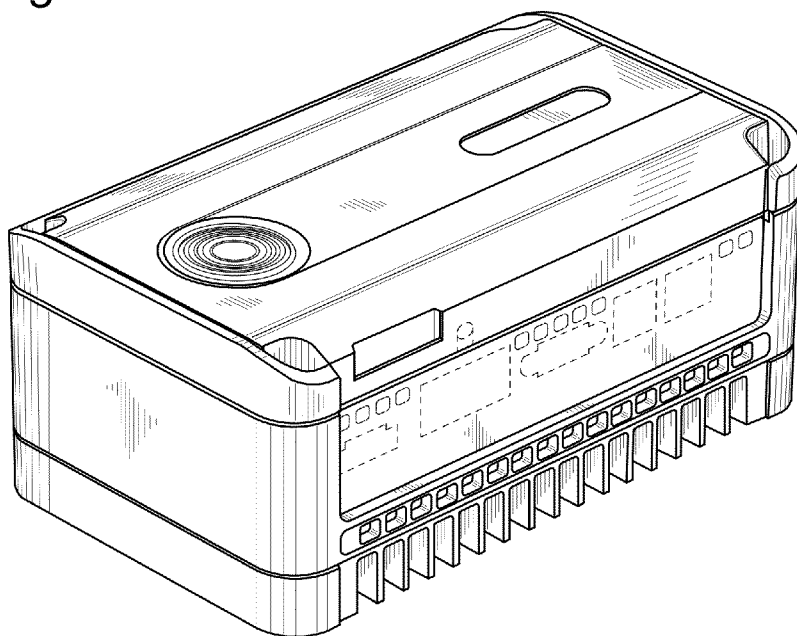


Figure 12

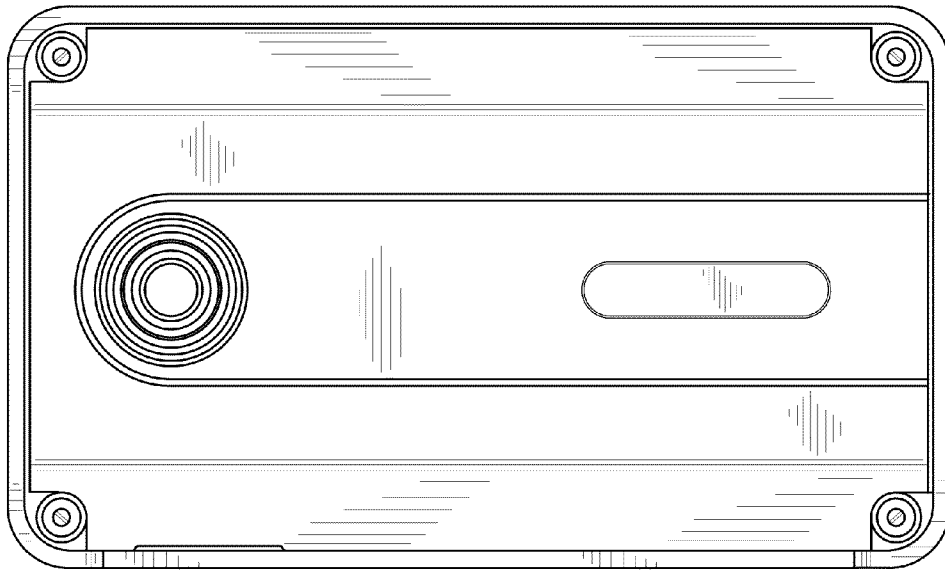


Figure 13

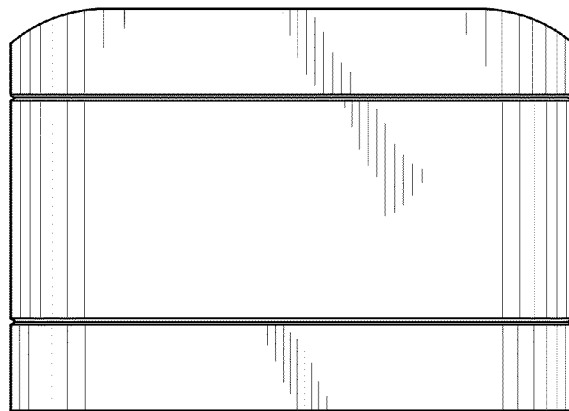


Figure 14

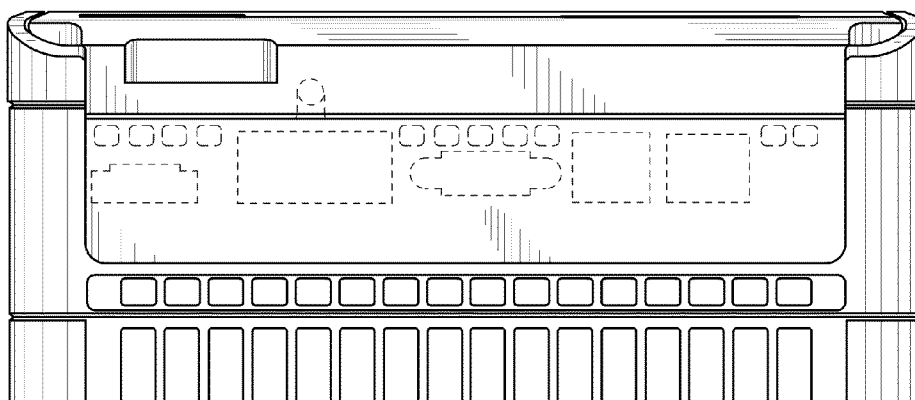


Figure 15

